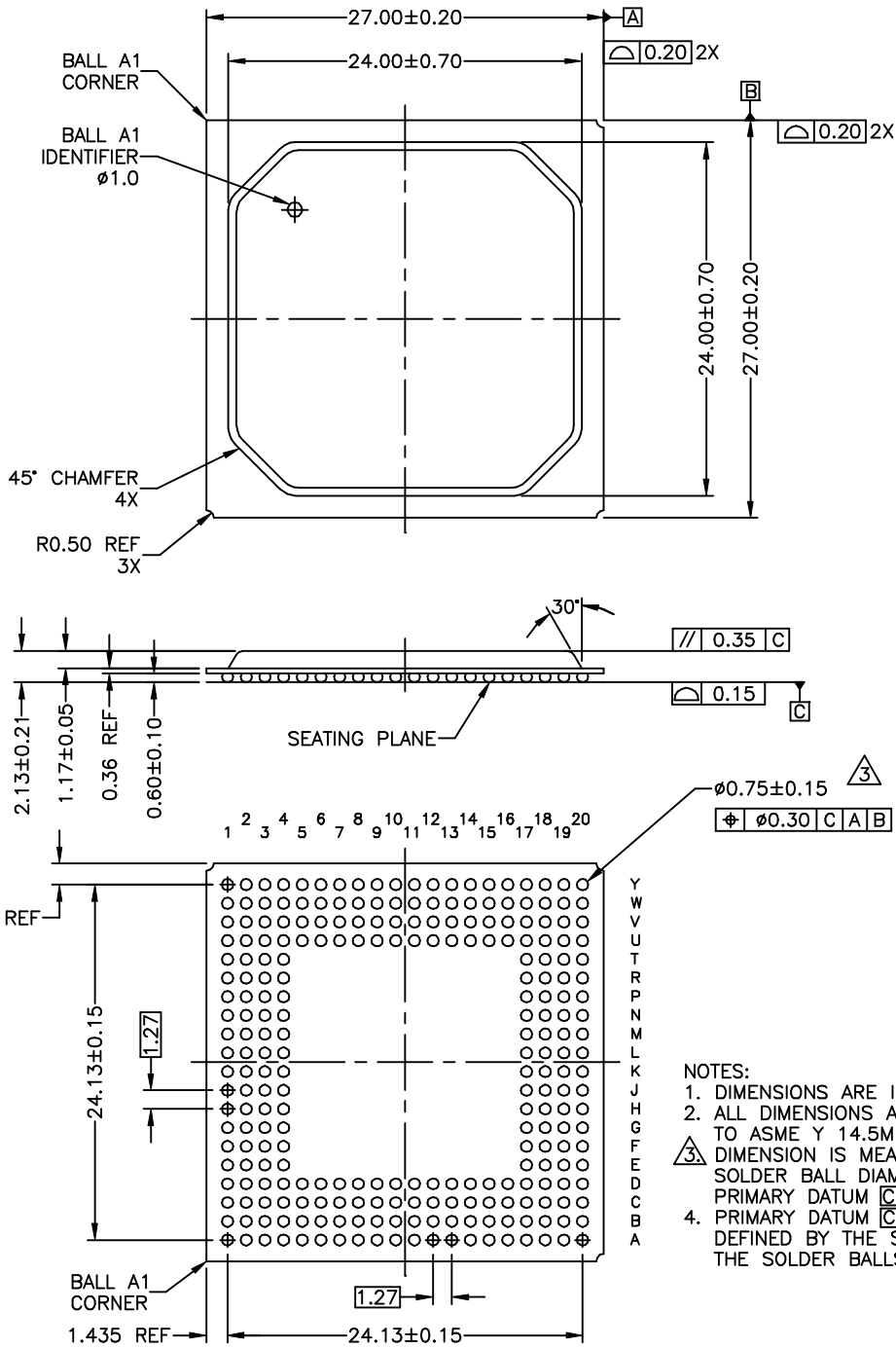




NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. ALL DIMENSIONS AND TOLERANCE CONFORM TO ASME Y 14.5M-1994.
3. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

SIGNATURE		DATE		 Dallas Semiconductor	
DOC. CONTROL:					
ENGR. MGR:				TITLE MARKETING OUTLINE - 256L PBGA(27x27) 1.27 PITCH, 2.13 THICK, 2 LAYER	
MFG. ENGR:					
CHECKED BY:					
DRAWN BY:		SIZE A	FSCM NO	PART NO.	REV A
DO NOT SCALE DWG.		SCALE 2/1		SHEET 1 OF 1	